

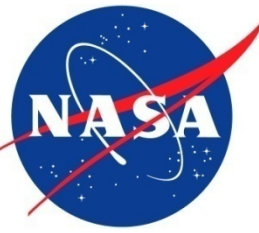


# What Can We Learn From Proton Recoils about Heavy-Ion SEE Sensitivity?

Ray Ladbury

NASA Goddard Space Flight Center

Radiation Effects and Analysis Group



# Abbreviations

CMOS—Complementary Metal Oxide Semiconductor

COTS—Commercial Off The Shelf

DUT—Device Under Test

E—Energy

$E_{\text{dep}}$ —Energy Deposited

FPGA—Field Programmable Gate Array

GCR—Galactic Cosmic Rays

GEDI—Global Ecosystem Dynamics Investigation (a Lidar instrument set to fly on the ISS)

ISS—International Space Station

LEO—Low-Earth Orbit

LET—Linear Energy Transfer

$\text{LET}_{\text{EQ}}$ —Equivalent Linear Energy Transfer

$\text{LET}_0$ —Onset LET

MOSFET—Metal-Oxide Semiconductor Field Effect Transistor

SEB—Single-Event Burnout

SEE—Single-Event Effects

SEGR—Single-Event Gate Rupture

SEL—Single-Event Latchup

SEU—Single Event Upset

Si—silicon

SOTA—State-Of-The-Art

SV—Sensitive Volume

TID—Total Ionizing Dose

TNS—Transactions on Nuclear Science

WC—Worst Case

Z—Atomic number of an element

$\forall$ —"For all"

$\alpha$  particle—two protons and two neutrons bound together into a particle identical to a helium nucleus

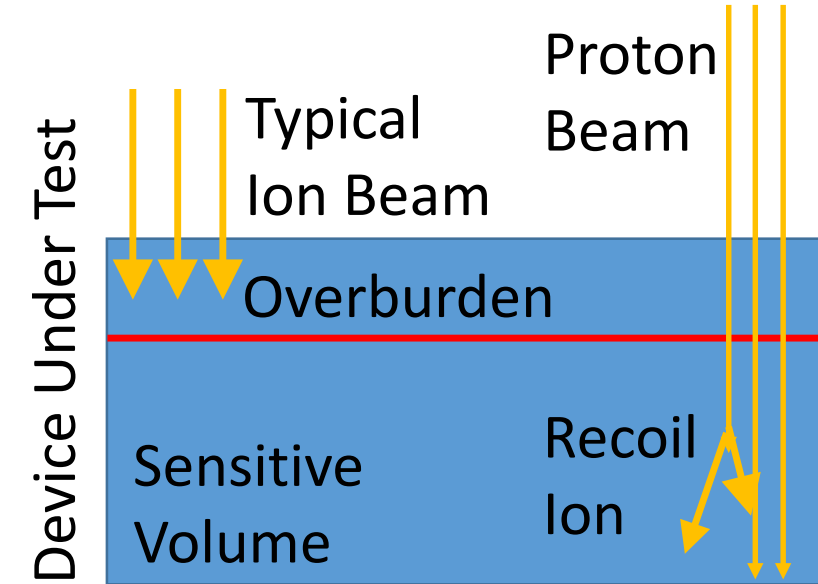
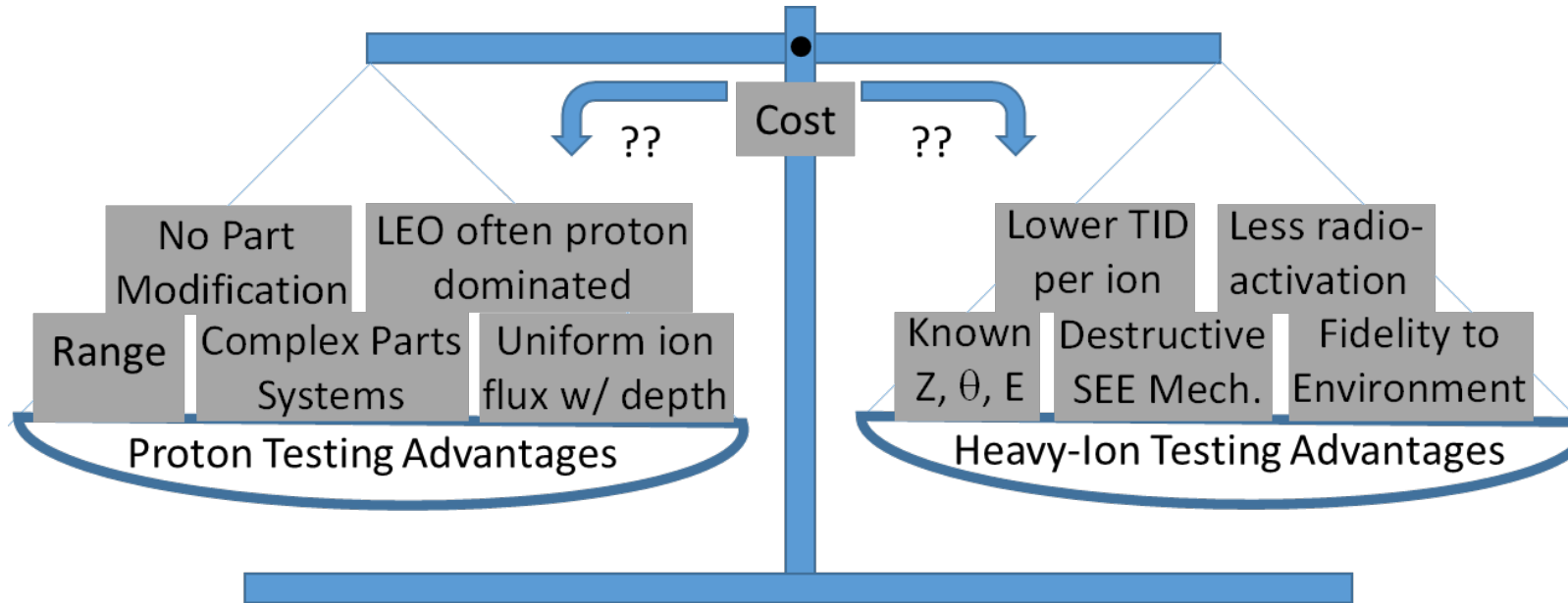
$\sigma$ —Cross Section

$\sigma_{\text{sat}}$ —Saturated Cross Section

$\theta$ —Angle

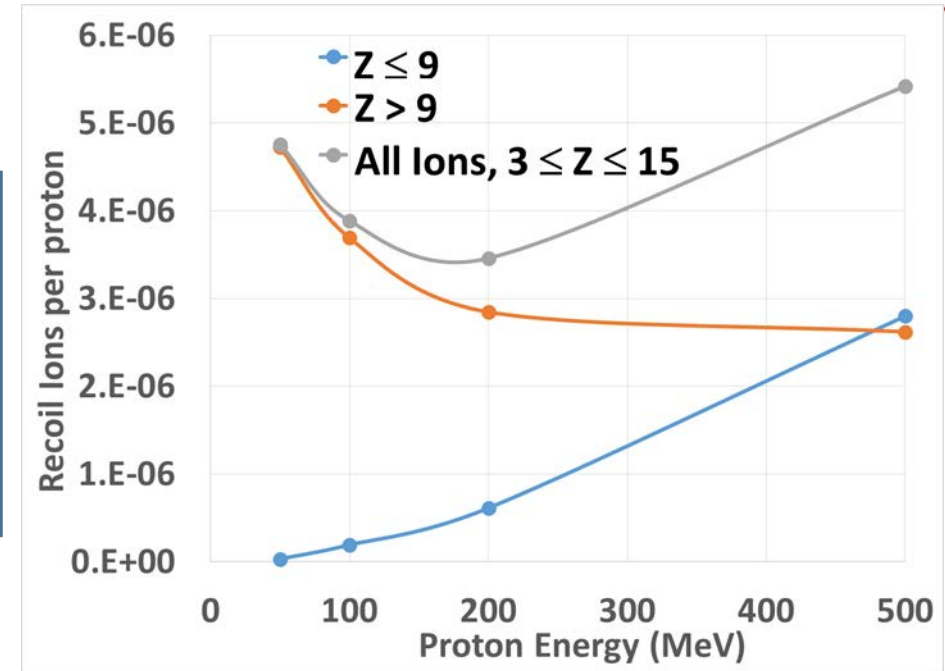
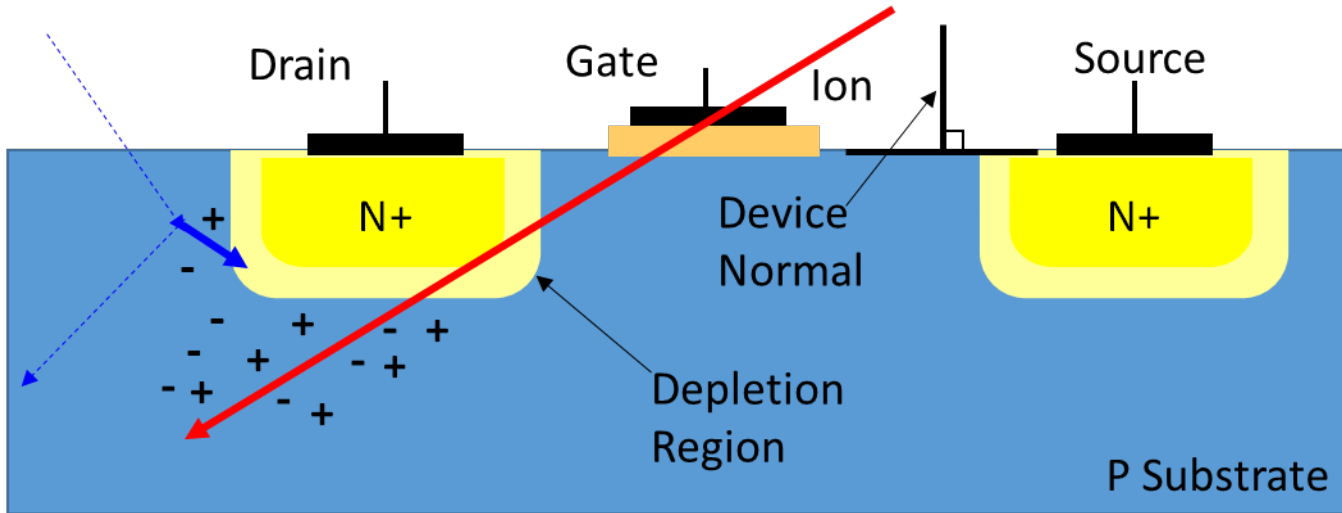


# SEE Testing: Protons or Heavy Ions?

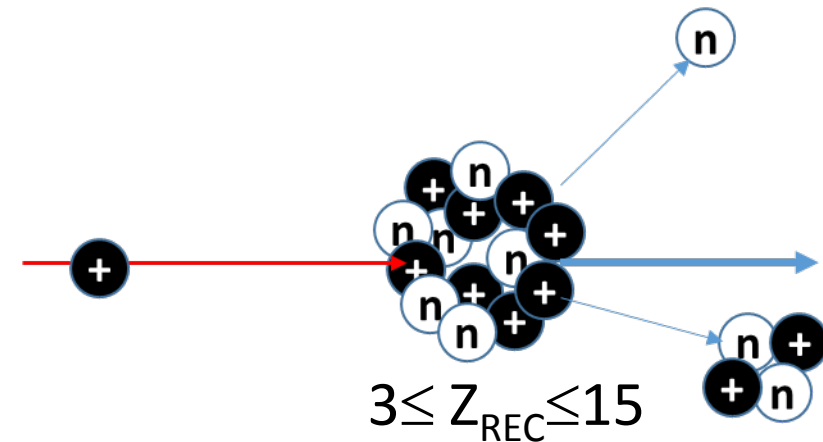


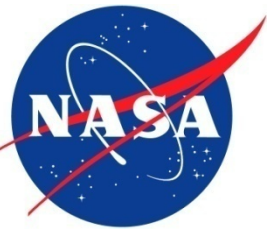
- Heavy-ion SEE testing poses well known difficulties:
  - Expensive in terms of cost and schedule
  - Often requires extensive modification of part to ensure beam reaches device sensitive volumes
  - Mainly geared to testing components rather than systems
- Protons potentially offer relief from many of these issues

# Physics of Proton-Si Recoils

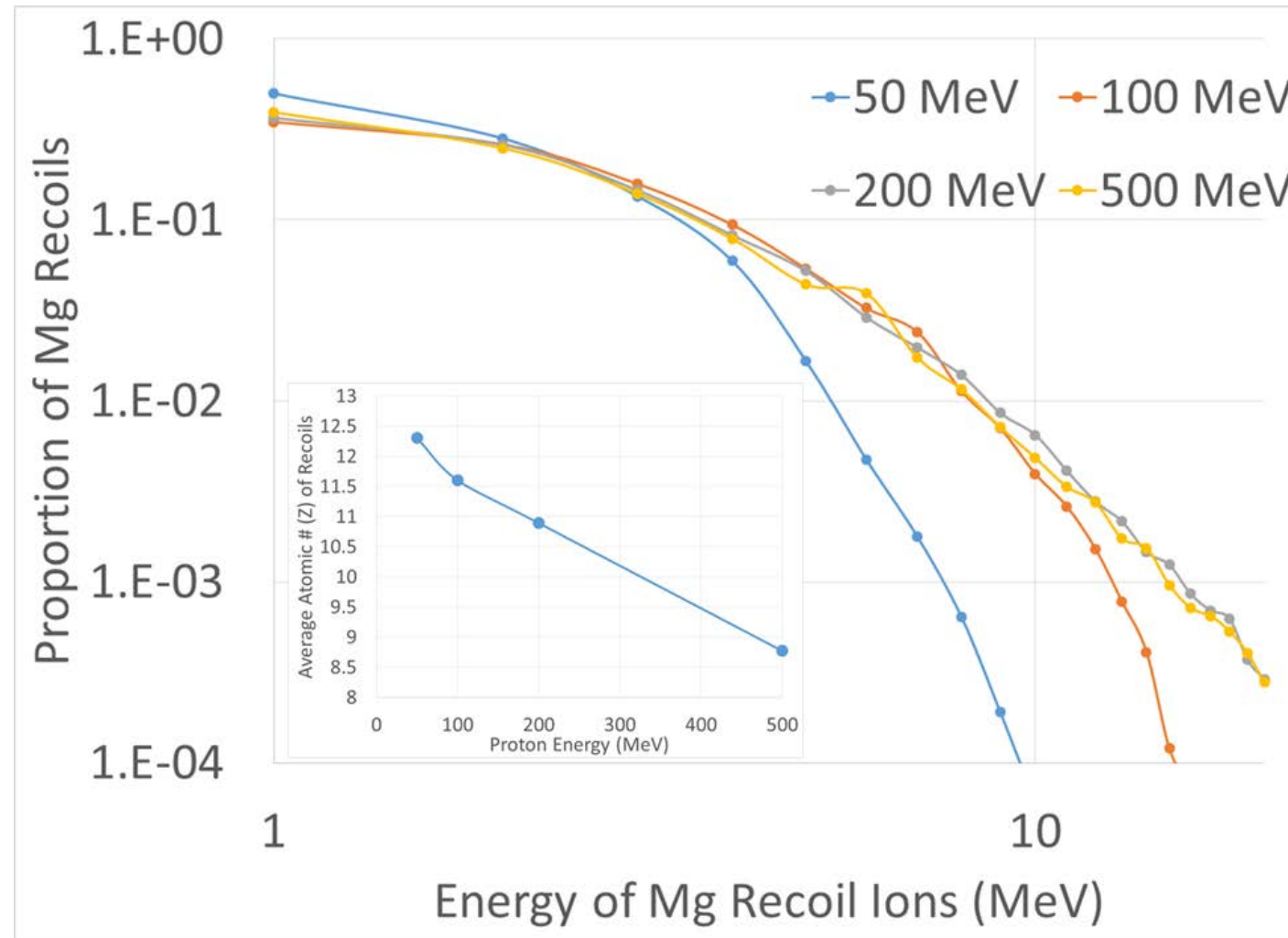


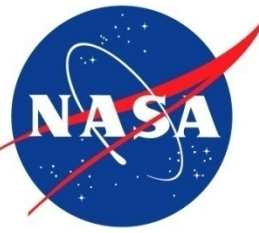
- Protons cause SEE via indirect ionization
  - Recoil ion from p-Si collision provides ionization for SEE
  - Proton accelerates and excites the ion, which then de-excites, emitting nuclear fragments  $n$ ,  $p$  and  $\alpha$ )  $\rightarrow 3 \leq Z_{\text{REC}} \leq 15$
  - Recoil ions have low energy/short range,  $3 \leq Z_{\text{REC}} \leq 15$  and are emitted over a range of angles
  - Evaporation particles ( $\alpha$  particles) may be important for very sensitive devices





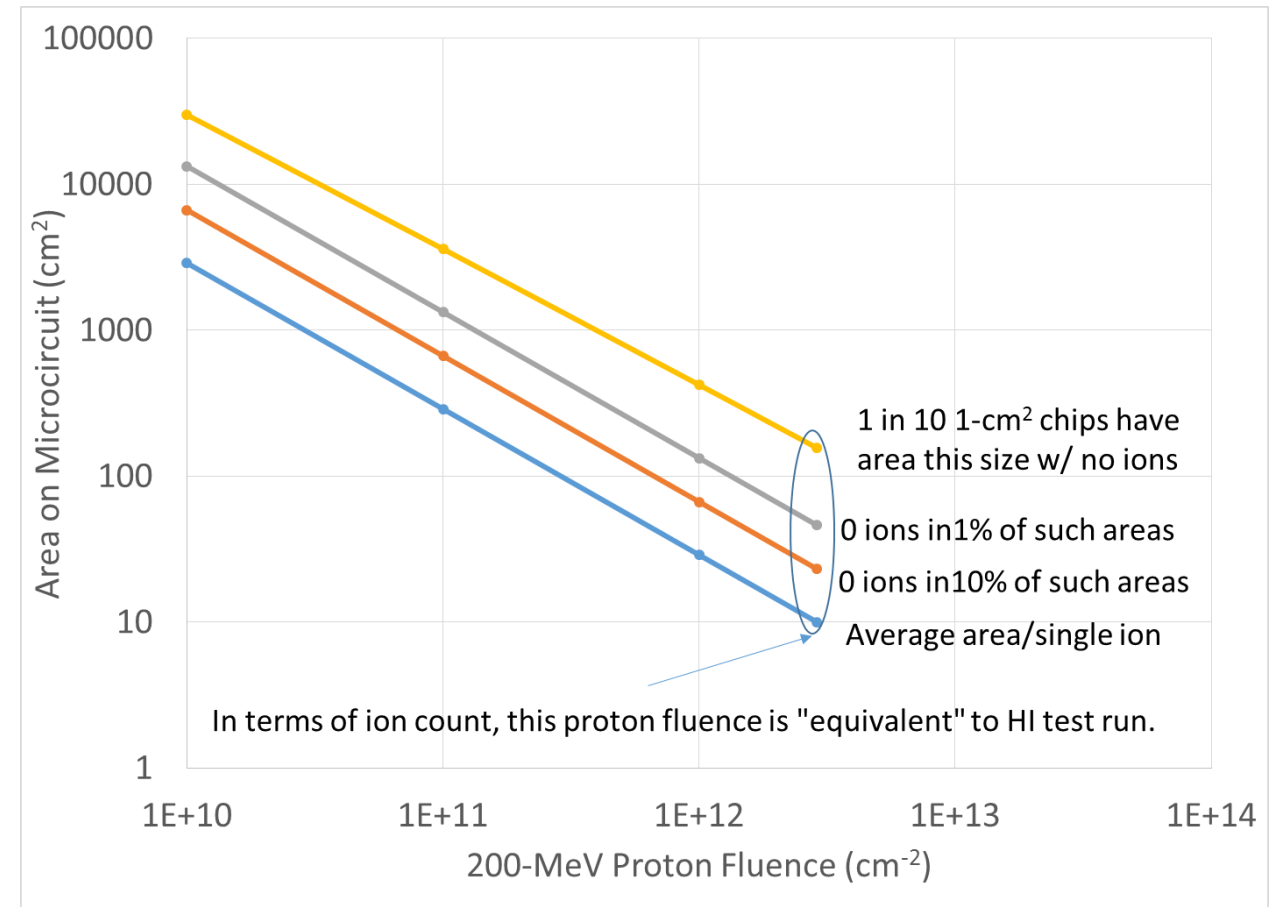
# Why 200 MeV protons?



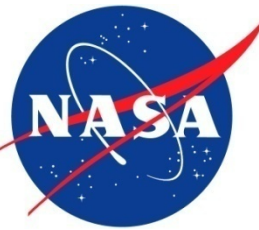


# Proton Fluence: How Much is Enough?

- SEE test goal
  - Realize representative sample of error modes that might realistically occur
  - SEE are Poisson; so they can occur any time, even if they are low probability
- JESD-57 goal of establishing “...with high statistical confidence that all sensitive volume on the DUT have been irradiated...” likely not feasible for current parts
  - Finite fluence + small feature sizes mean some features will be missed
  - How repetitive is device architecture?
  - Complicated devices (e.g., FPGAs, Processors, etc.) need higher fluence than simple ones (e.g., simple memory, logic...)



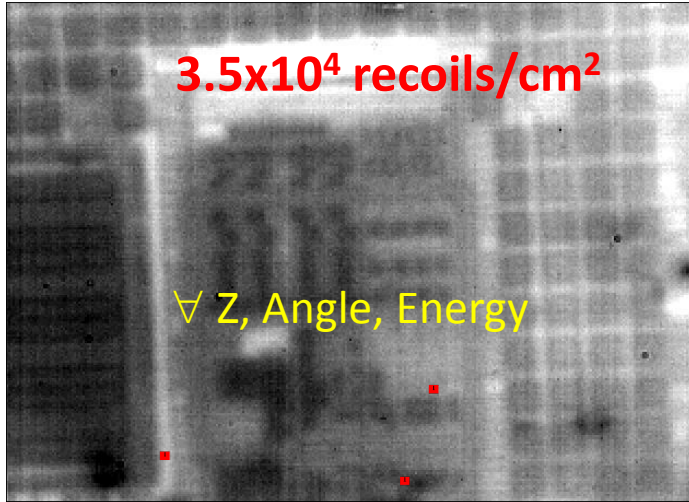
# What Proton Fluence is Enough?



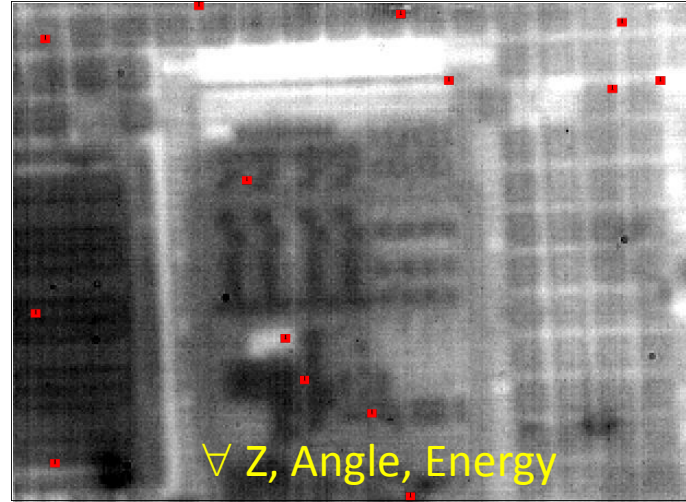
Infrared micrograph of a portion of a 512 Mb SDRAM  $\sim 60 \times 70 \mu\text{m}^2$

- Shows both memory cells and control logic (10 yr. old tech.) Red spots are ion hits

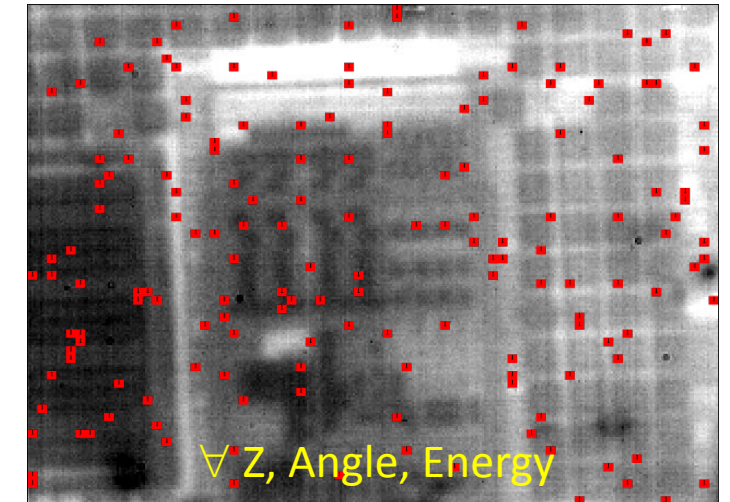
$10^{10}$  200 MeV protons/cm<sup>2</sup>



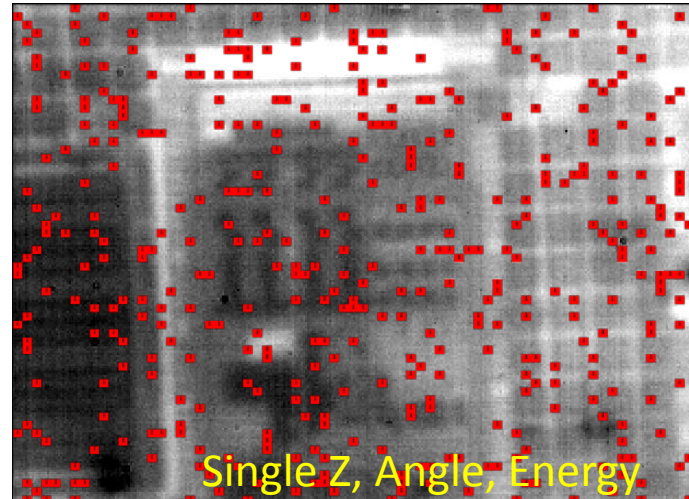
$10^{11}$  200 MeV protons/cm<sup>2</sup>



$10^{12}$  200 MeV protons/cm<sup>2</sup>



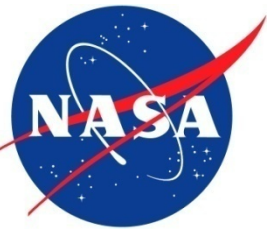
20% of areas this size get 0 hits for  $10^{10} \text{ cm}^{-2}$



Coverage from  
 $10^7$  heavy ions/cm<sup>2</sup>

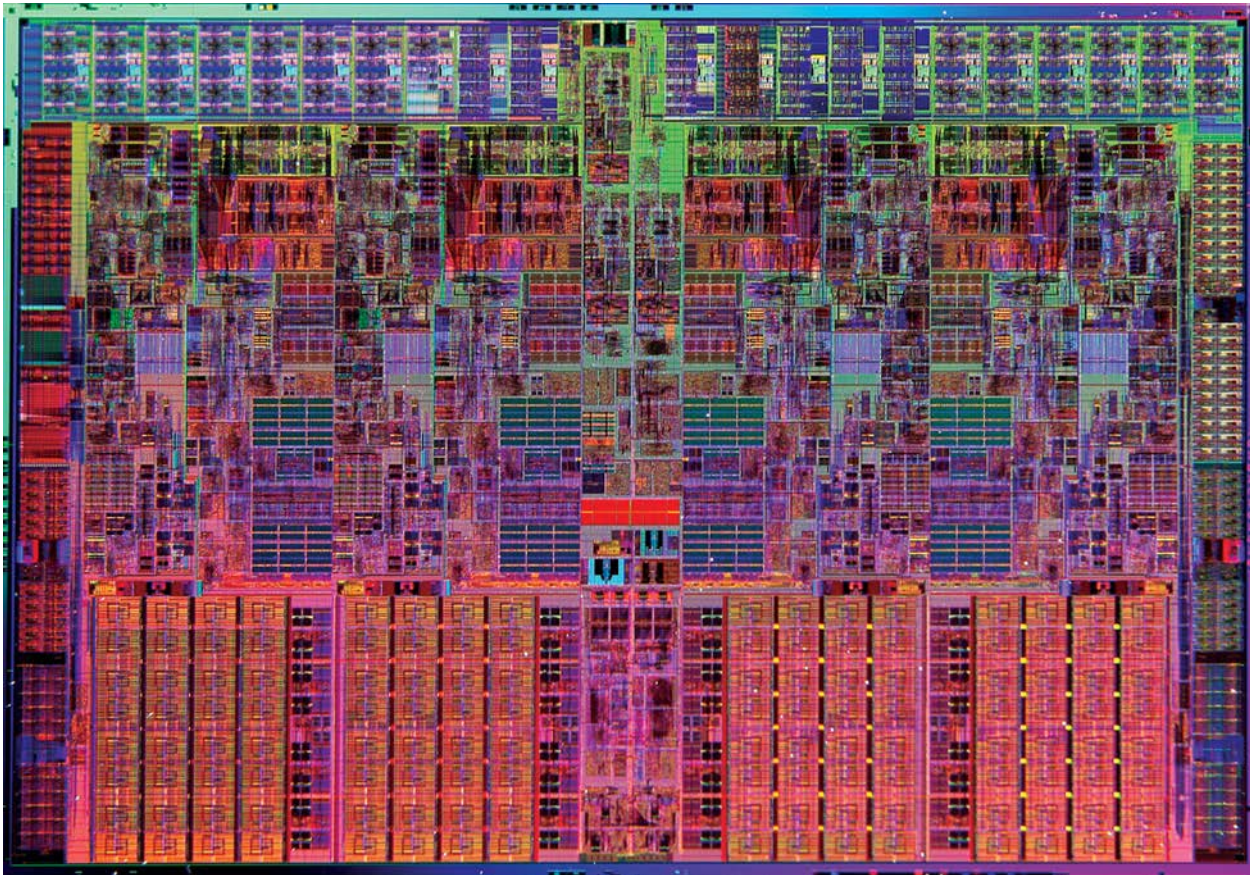


# What About More Recent Technologies?



## Intel I7 Processor (2008)

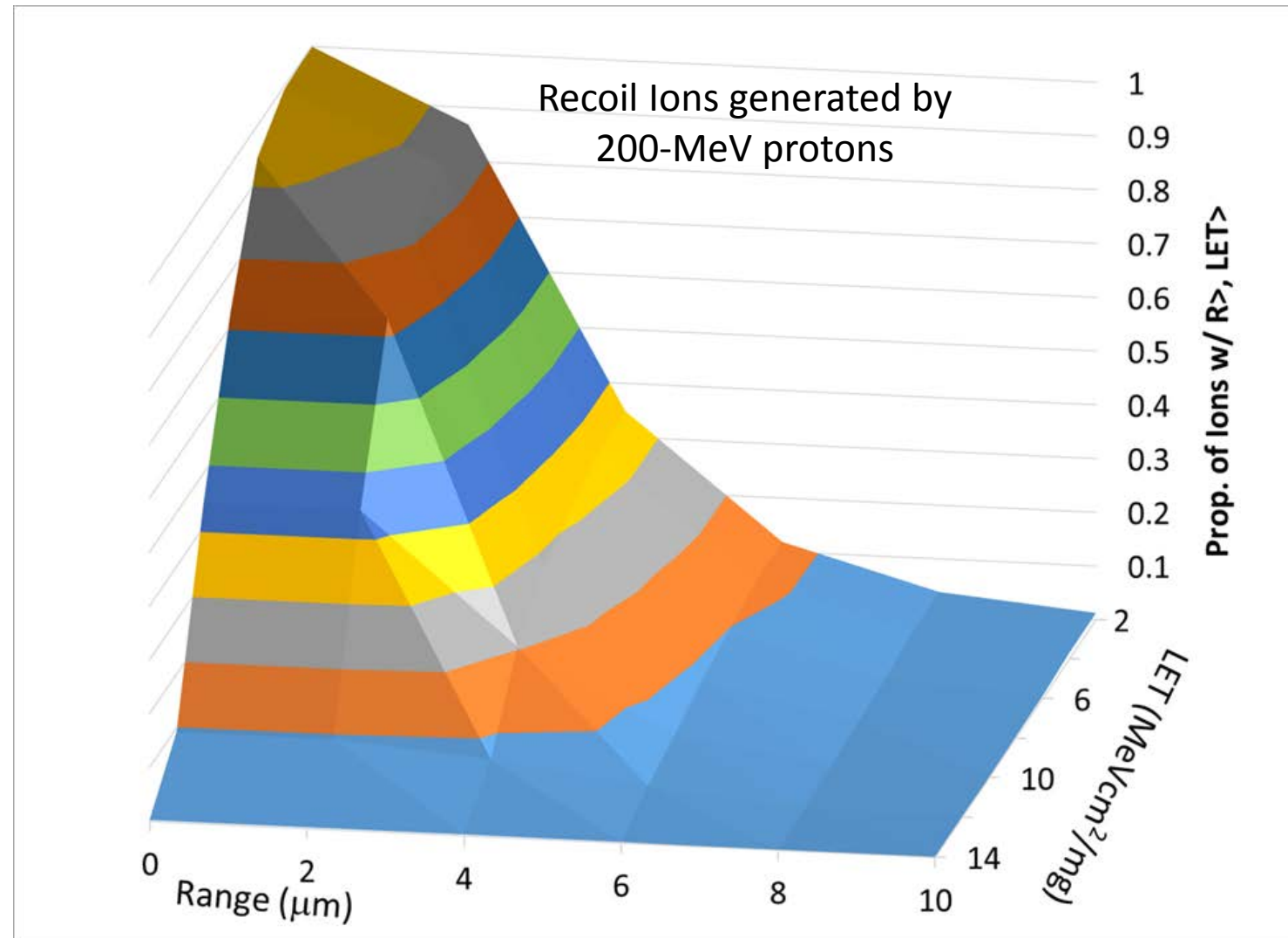
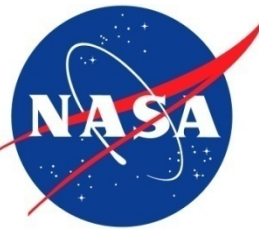
Process Size: 45 nm  
Transistors: 731 million  
Die Size: 263 mm<sup>2</sup>



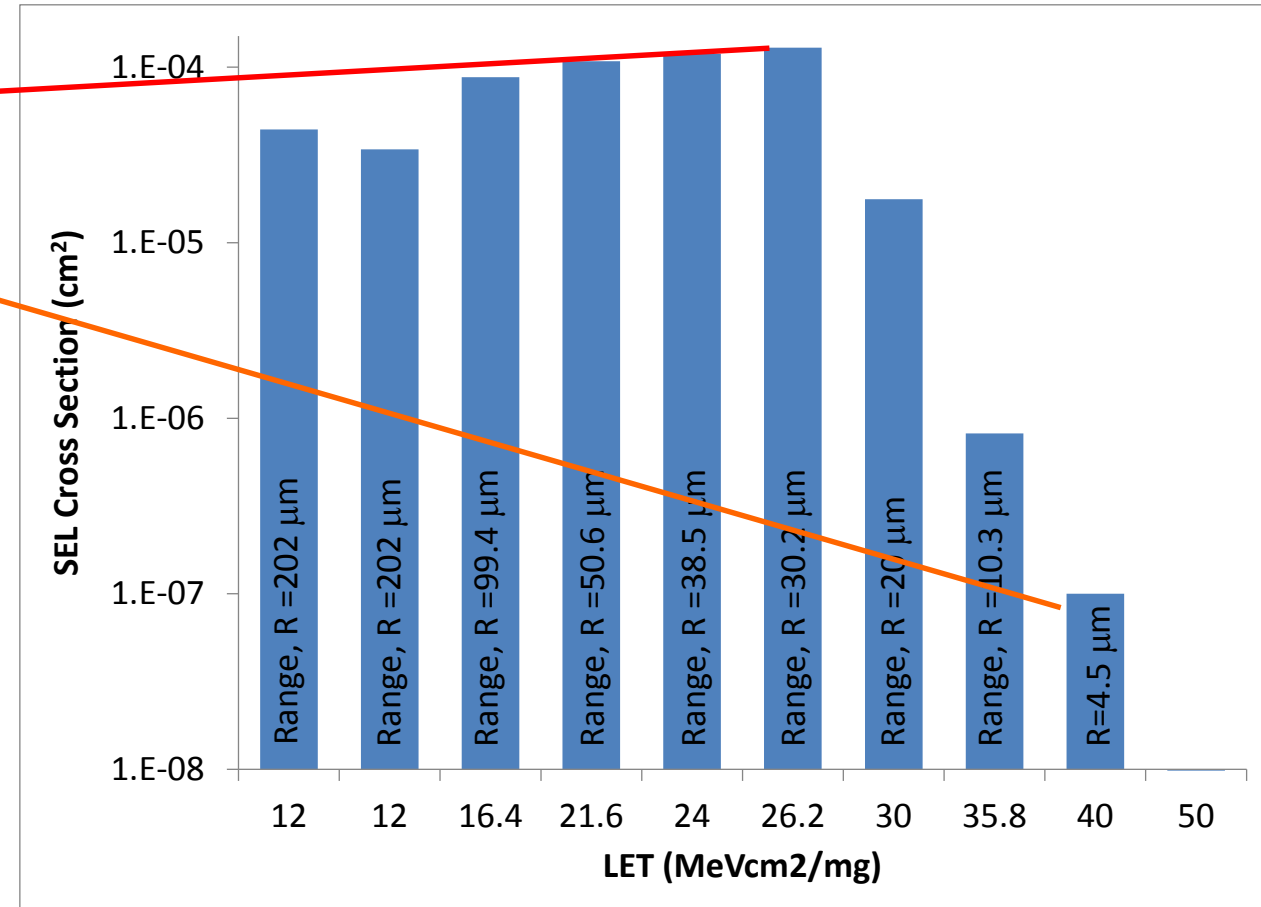
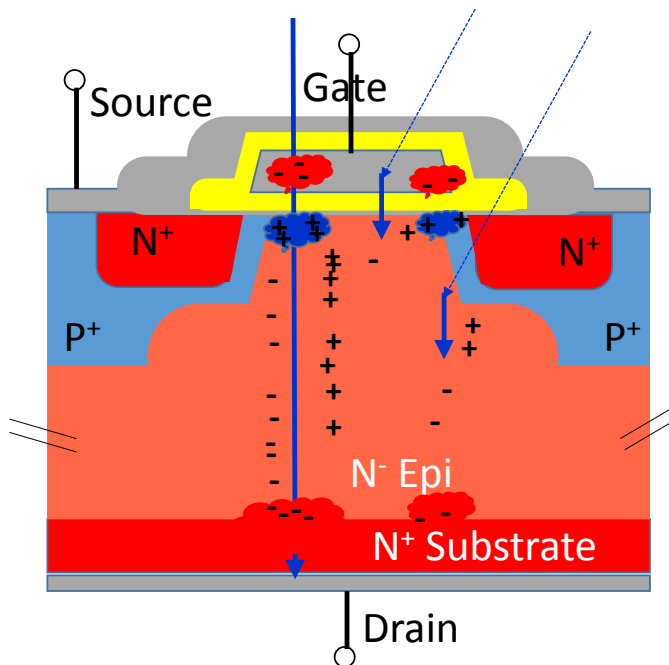
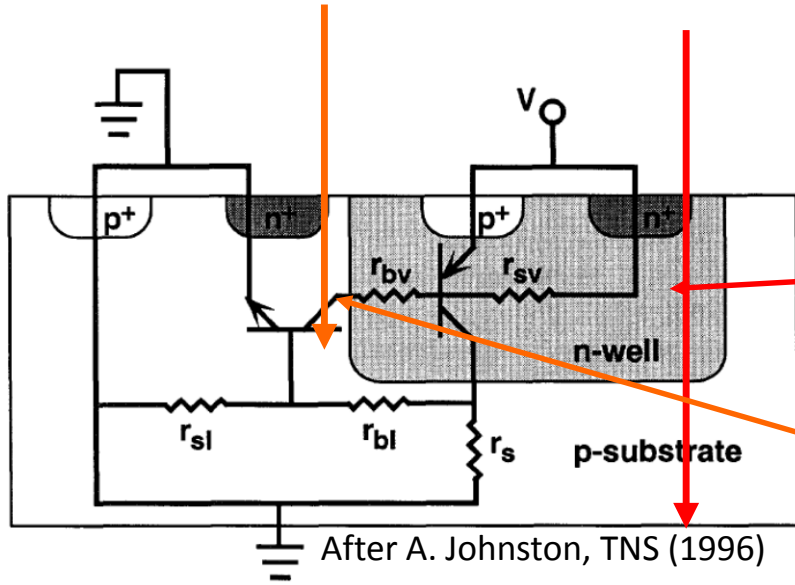
- For  $10^{10}$  200-MeV protons/cm<sup>2</sup>
  - Average area per ion ( $\sim 2890 \mu\text{m}^2$ ) contains about 7800 transistors
  - For comparison, an Intel 8080 8-bit processor had  $\sim 6000$  transistors.
  - 10% chance no ions strike an area  $> 70000 \mu\text{m}^2$  containing  $> 90000$  transistors (half way between an Intel 80186 and 80286 (16-bit))
- For  $10^{12}$  200-MeV protons/cm<sup>2</sup>
  - Average area per ion contains 80 transistors
  - 10% chance of missing area w/ 1250 transistors
- Heavy-ion test run ( $10^7$  ions/cm<sup>2</sup>)
  - Transistor counts in  $10 \mu\text{m}^2$  are 28.9 and 460
- But!
  - Recoil ions not all created equal
  - Produced w/ range of Z, energy, LET and angle



# Recoil Ion Fluence Falls Rapidly If We Require Greater Range



# Destructive SEE and Ion Range



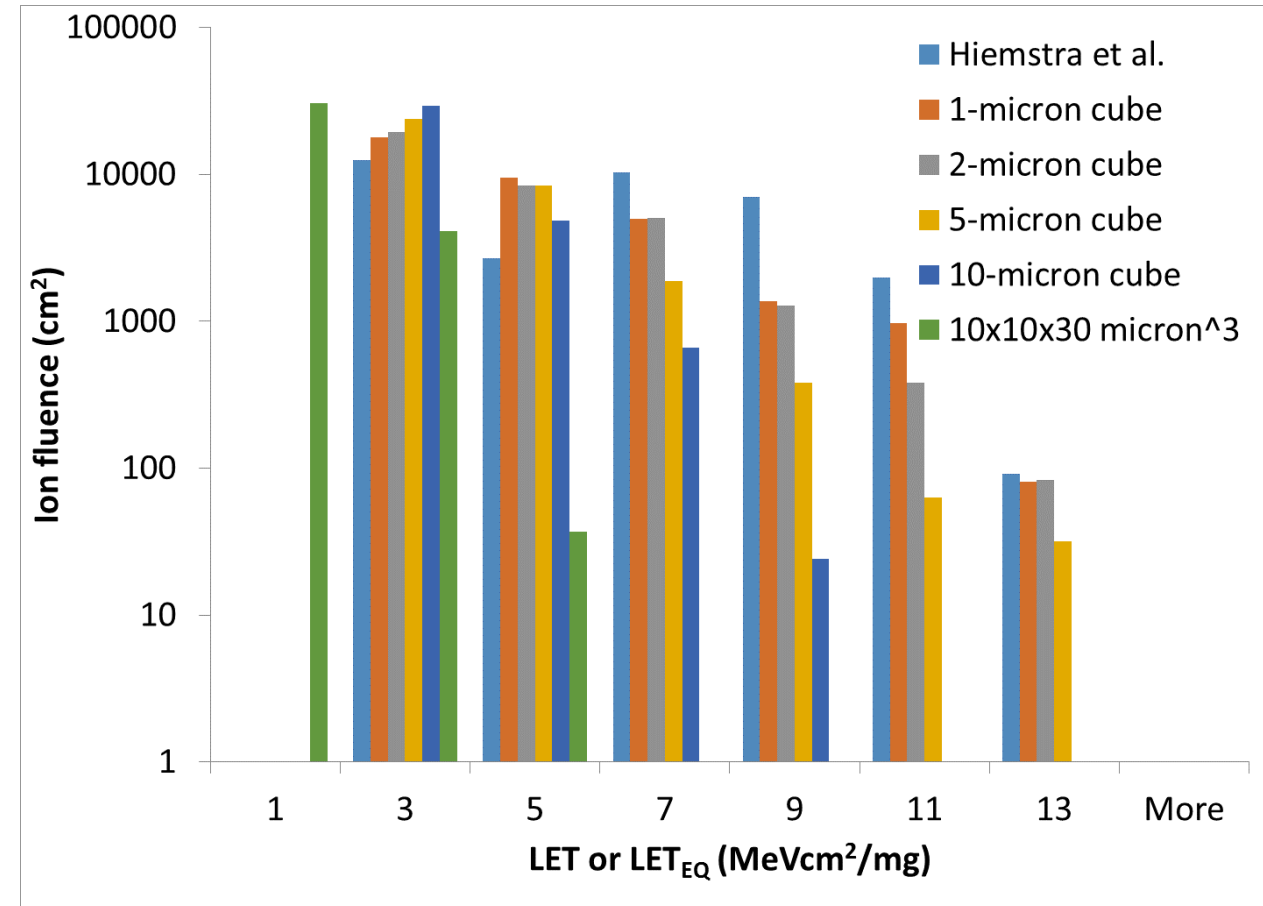
Data from C. Marshall et al., IEEE TNS Vol. 57, No. 6, pp. 3078-3086 (2010)

# Dealing with Range Limitation

- LET dependence is an approximation
  - SEE susceptibility depends on charge collected in the sensitive volume
  - For recoil ions in deep SV, charge deposited limited by range, not LET
- Introduce equivalent LET,  $LET_{EQ}$

$$LET_{EQ} = \frac{E_{dep}}{(\rho \times z)}$$

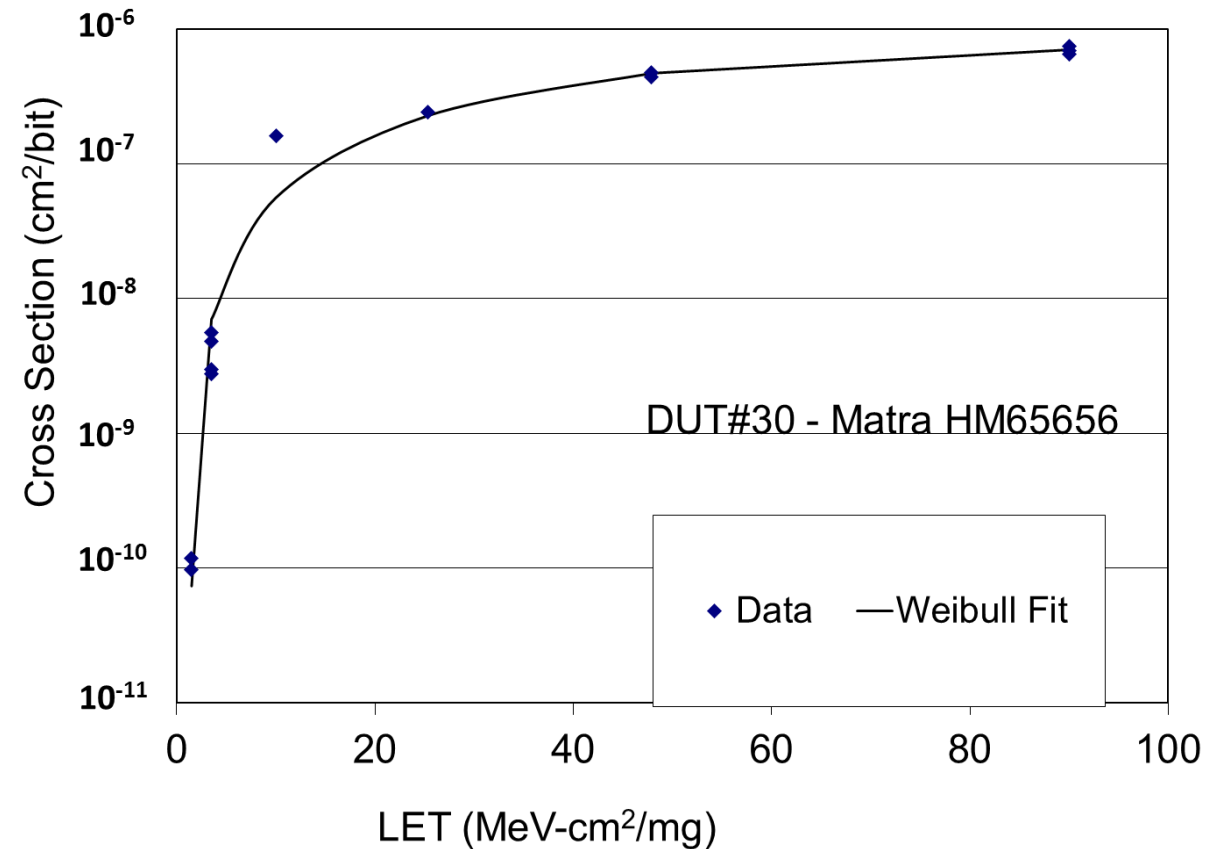
- $E_{dep}$  is energy deposited in SV by ion
- $\rho$  is density of Si,  $z$  is SV depth
- $LET_{EQ}$  is the ion's average LET if it reaches the bottom of the SV
- $LET_{EQ}$  is the constant LET an ion would need to deposit  $E_{dep}$  in SV assuming normal incidence

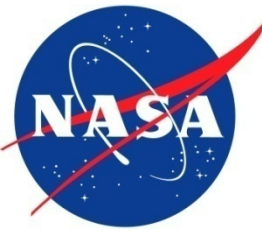




# But: Not Every Ion Is Equally Likely to Cause an SEE

- Even for shallow SV, low-LET ions are less likely to cause an SEU
  - Can derate fluence at each LET/LET<sub>EQ</sub> by Weibull factor
$$Weibull(LET_{EQ} - LET_0, W, s)$$
  - Results in an equivalent fluence
  - Can be used to find worst-case rate for a null result at a given confidence level.
- Matra 256 K SRAM has limiting cross section of 0.2 cm<sup>2</sup>
- Predict ~131 upsets with 10<sup>10</sup> 200-MeV protons
  - Limiting cross section measured by B. Doucin ('95 RADECS) ~2x10<sup>-8</sup> cm<sup>2</sup>/dev (within a factor of 2)

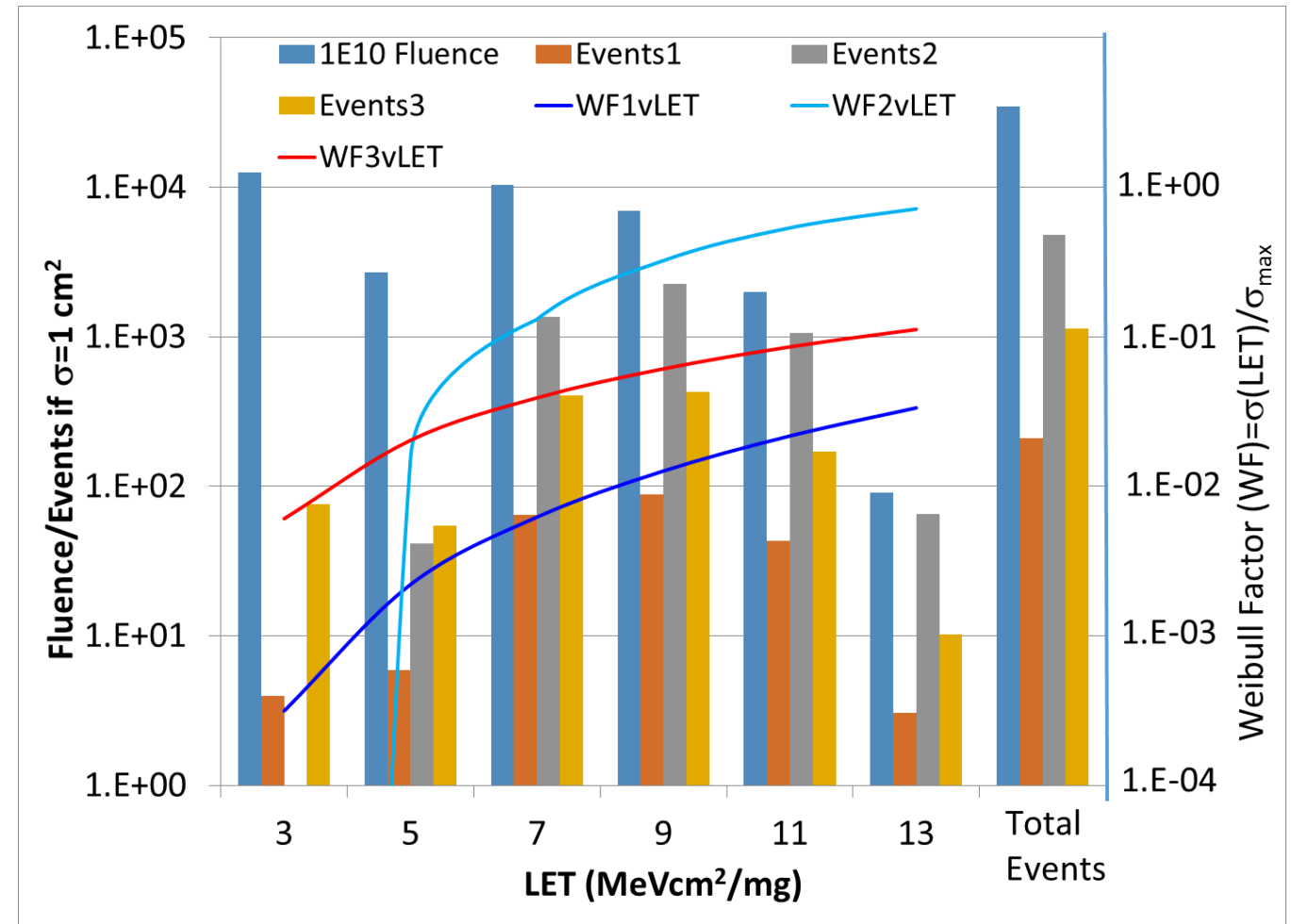




# Effect of Cross Section vs. LET Shape

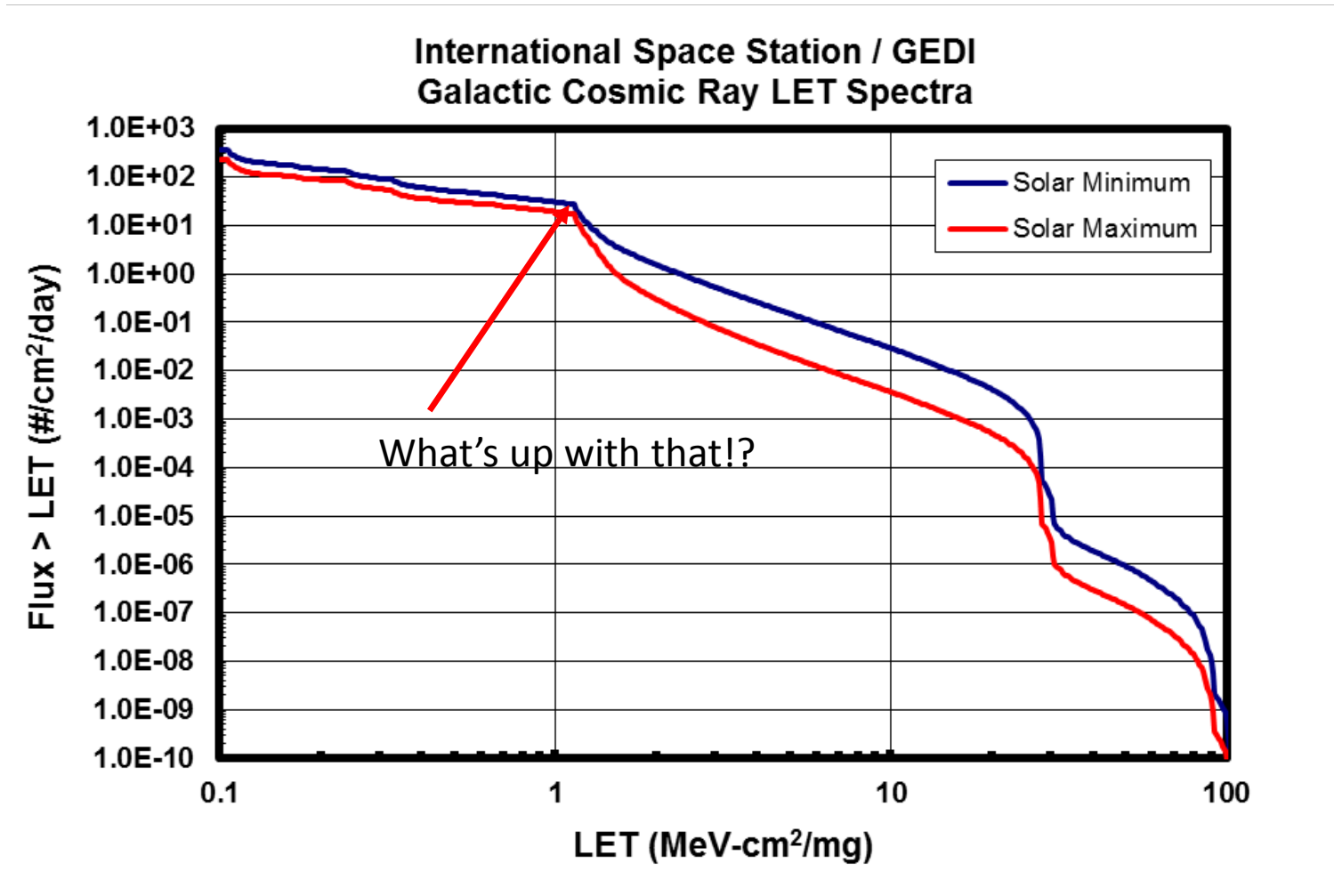
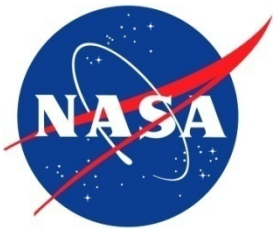
- Inferring proton susceptibility from heavy-ion data is straightforward
  - Use  $\sigma$  vs. LET and recoil ion spectrum to estimate expected events  $\langle N \rangle$
- Constrain rate w/ proton data
  - Recoil fluences +  $LET_0$ ,  $s$  and  $W$  set relative contributions
  - Choose  $\sigma_{sat}$  so probability of seeing no events  $> 10\% \rightarrow \langle N \rangle = 2.3$
  - Highest rate bounds null result in proton test at the 90% confidence level

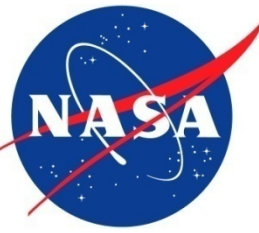
| WC Rate  | $\langle N \rangle @ 1 \text{ cm}^2$ | Per bit cs | s   | W  | LET <sub>0</sub> |
|----------|--------------------------------------|------------|-----|----|------------------|
| 0.000856 | 32226.38947                          | 1.19E-07   | 0.5 | 5  | 0.5              |
| 0.000159 | 18577.27893                          | 1.28E-08   | 0.5 | 5  | 1.5              |
| 6.17E-05 | 12970.74197                          | 3.47E-09   | 0.5 | 5  | 2.5              |
| 4.5E-05  | 8703.467731                          | 1.7E-09    | 0.5 | 5  | 3.5              |
| 3.75E-05 | 6097.639989                          | 9.91E-10   | 0.5 | 5  | 4.5              |
| 0.000818 | 24892.46517                          | 8.82E-08   | 0.5 | 10 | 0.5              |
| 0.000153 | 14486.82459                          | 9.57E-09   | 0.5 | 10 | 1.5              |
| 6.09E-05 | 10092.54183                          | 2.66E-09   | 0.5 | 10 | 2.5              |
| 4.47E-05 | 6765.500655                          | 1.31E-09   | 0.5 | 10 | 3.5              |
| 3.75E-05 | 4714.079379                          | 7.64E-10   | 0.5 | 10 | 4.5              |





ISS SEE Rates Increase Rapidly as  $LET_0$  Decreases from 2 to 0.5 (MeV-cm<sup>2</sup>/mg)

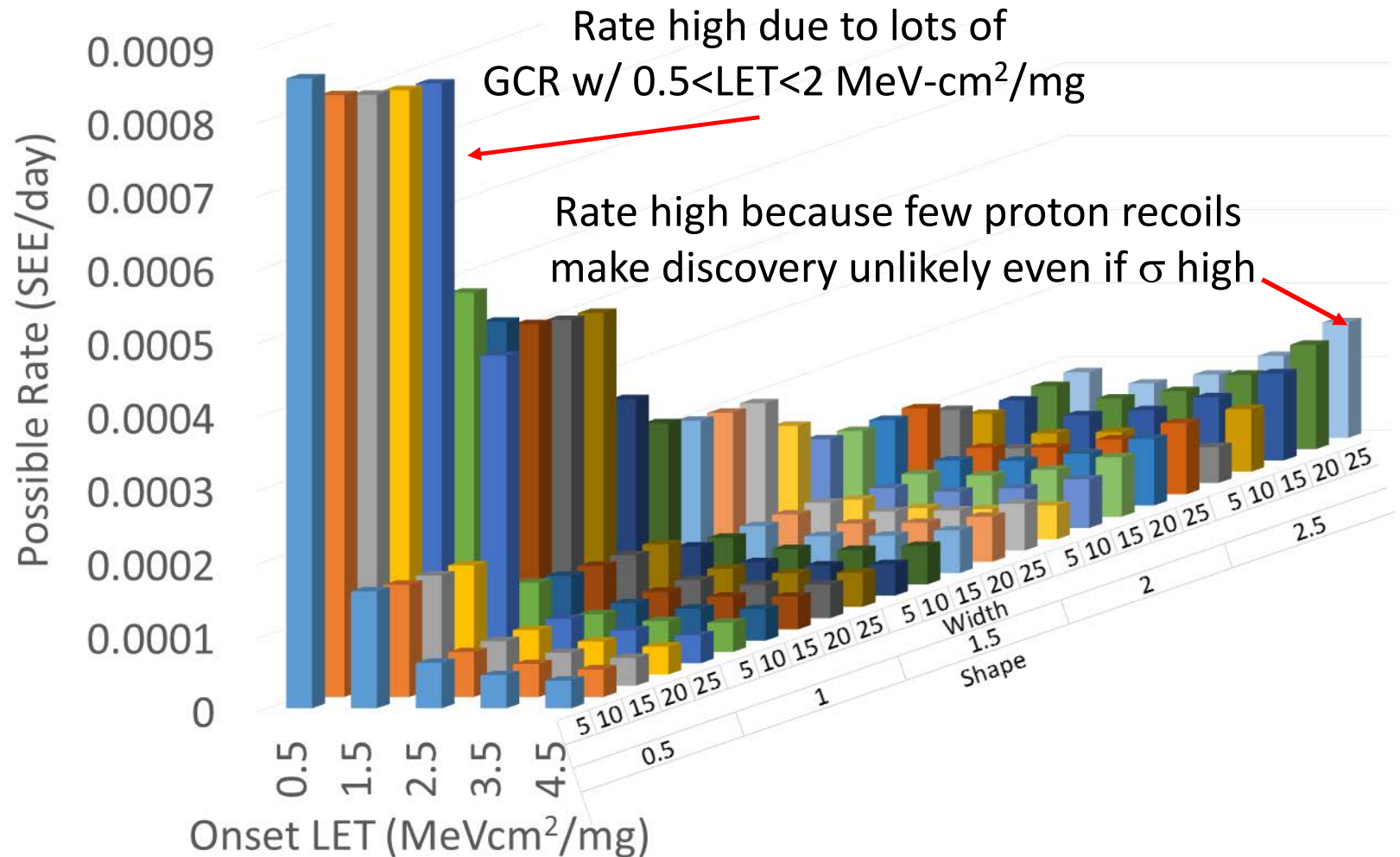




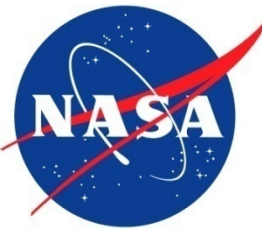
# How High Can the SEE Rate Be if We Didn't See It in the Test?

- Recoil fluence vs. LET due to nuclear physics
  - $3 < Z < 15$ —produce LET from 2-12 MeV-cm<sup>2</sup>/mg
  - $Z=2$  due to evaporation process→mainly  $0.5 < \text{LET} < 2$
  - Ions w/  $0.5 < \text{LET} < 2 \sim 1.6\times$  more than w/  $2 < \text{LET} < 12$
- For GCR @ ISS  $\sim 30\times$  more ions w/  $0.5 < \text{LET} < 2$  than from  $2 < \text{LET} < 12$
- More SOTA COTS have onset  $\text{LET} < 2 \text{ MeV-cm}^2/\text{mg}$ 
  - Proton test method may be less effective for latest generation parts

Select  $\sigma$  so  $>10\%$  chance of seeing 0 events w/  $10^{10}$  200-MeV p/cm<sup>2</sup> test.



# How Do We Better Bound Heavy-Ion SEE w/ Proton Testing?



- First, don't try to make protons do what they cannot do well
  - If SEGR/SEB are probable concerns, recommend a go/no-go heavy-ion test
    - WC voltages, single ion w/ predetermined LET, Z and range
  - For SEL in bulk CMOS where depth of SV likely  $>5\text{-}10\text{ }\mu\text{m}$ , recommend go/no-go heavy-ion test
    - Especially if many copies of same part used in design
    - WC temperature, bias, single-ion w/ predetermined LET, range.
  - May also be inappropriate for studying multi-bit upsets and upsets in technologies with deep SV (e.g. SiGe)
- Increase proton fluence
  - Ensures errors/failures observed during test more likely to resemble those seen on orbit
  - Reduces bounds on rates for “unknown SEE modes”
    - True for both high  $\text{LET}_0$  and low  $\text{LET}_0$
  - If dose is too high, can test multiple copies of device/board/box
    - High-energy neutron testing may also be an option
- Proton SEE data must be analyzed conservatively
  - Using  $\text{LET}_{\text{EQ}}$  of recoils reduces chances of underestimating SEE sensitivity
    - $\text{LET}_{\text{EQ}}$  better reflects physics of SEE modes and reduces to LET if SV for SEE mode is thin
  - Understanding device technologies can improve bounds on SEE rates achievable by proton testing